

Title (en)  
METHOD FOR COVERING COPPER WITH PATINA

Title (de)  
METHODE ZUR PATINIERUNG VON KUPFER

Title (fr)  
METHODE DE PATINAGE DU CUIVRE

Publication  
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Application  
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Abstract (en)  
[origin: WO2005049889A1] The invention relates to a method for covering copper or copper alloy articles with patina. The articles to be covered with patina are treated with a preferably copper and zinc ion-containing, preferably aqueous patination solution and are then subjected to a so-called maturation process which is especially carried out in a climatic chamber.

IPC 8 full level  
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